



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PART NUMBER	ITEM ① BODY	ITEM ② CONTACT	ITEM ③ INSULATOR	ITEM ④ INSULATOR	PACKAGING
133-3711-311	BRASS GOLD PL .00001 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	BERYLLIUM COPPER GOLD PL .00003 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	TEFLON	TEFLON	BULK PACK 25 PCS.
133-3711-312	BRASS GOLD PL .00001 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	BERYLLIUM COPPER GOLD PL .00003 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	TEFLON	TEFLON	TAPE AND REEL 750 PCS. PER FIG 1
133-3711-315	BRASS NICKEL PL .0001 MIN OVER COPPER PL .00005 MIN	BERYLLIUM COPPER GOLD PL .00003 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	TEFLON	TEFLON	BULK PACK 25 PCS.
133-3711-316	BRASS NICKEL PL .0001 MIN OVER COPPER PL .00005 MIN	BERYLLIUM COPPER GOLD PL .00003 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	TEFLON	TEFLON	TAPE AND REEL 750 PCS. PER FIG 1
133-3711-317	BRASS TIN PL .00015 MIN OVER NICKEL PL .00003 MIN OVER COPPER PL .00003 MIN	BERYLLIUM COPPER GOLD PL .00003 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	TEFLON	TEFLON	BULK PACK 25 PCS.
133-3711-318	BRASS TIN PL .00015 MIN OVER NICKEL PL .00003 MIN OVER COPPER PL .00003 MIN	BERYLLIUM COPPER GOLD PL .00003 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	TEFLON	TEFLON	TAPE AND REEL 750 PCS. PER FIG 1

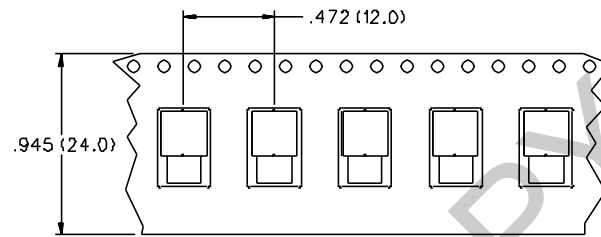
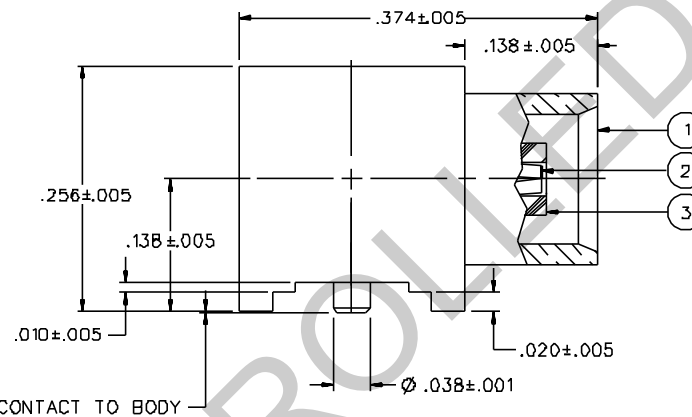


FIG 1
2:1



NOTES:

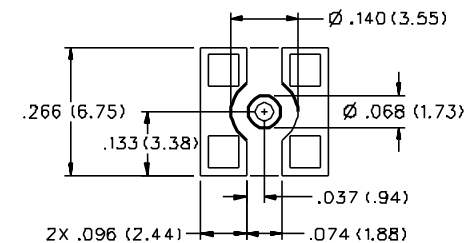
1. SPECIFICATIONS:

IMPEDANCE: 50 OHMS
 FREQUENCY RANGE: 0-6 GHz
 VSWR: NOT APPLICABLE
 WORKING VOLTAGE: 335 VRMS MAX AT SEA LEVEL
 DIELECTRIC WITHSTANDING VOLTAGE: 1000 VRMS MIN AT SEA LEVEL
 INSULATION RESISTANCE: 10000 MEGOHM MIN
 CONTACT RESISTANCE:
 CENTER CONTACT - INITIAL 5 MILLIOHM MAX, AFTER ENVIRONMENTAL 8 MILLIOHM MAX
 OUTER CONDUCTOR - GOLD PLATED INITIAL 1 MILLIOHM MAX, AFTER ENVIRONMENTAL 1.5 MILLIOHM MAX
 NICKEL AND TIN PLATED INITIAL 2.5 MILLIOHM MAX, AFTER ENVIRONMENTAL 3.5 MILLIOHM MAX
 BRAID TO BODY - NOT APPLICABLE
 CORONA LEVEL: 250 VOLTS MINIMUM AT 70,000 FEET
 INSERTION LOSS: NOT APPLICABLE
 RF LEAKAGE: NOT APPLICABLE
 RF HIGH POTENTIAL WITHSTANDING VOLTAGE: 600 VRMS AT 4 AND 7 MHZ
 MECHANICAL:
 ENGAGE/DISENGAGE FORCE: 5.6 LBS MAX ENGAGEMENT
 1.0 LB MIN DISENGAGEMENT
 8.0 LBS MAX DISENGAGEMENT
 CONTACT RETENTION FORCE: NOT APPLICABLE
 CONTACT RETENTION TORQUE: NOT APPLICABLE
 COUPLING MECHANISM RETENTION: NOT APPLICABLE
 CABLE ACCEPTABILITY: NOT APPLICABLE
 CABLE HEX CRIMP SIZE: NOT APPLICABLE
 CABLE RETENTION: NOT APPLICABLE
 DURABILITY: 500 CYCLES MIN

ENVIRONMENTAL:

(MEETS OR EXCEEDS THE APPLICABLE PARAGRAPH OF MIL-PRF-39012)
 THERMAL SHOCK: MIL-STD-202, METHOD 107, CONDITION F
 OPERATING TEMPERATURE: -65 DEG C TO 165 DEG C
 CORROSION: MIL-STD-202, METHOD 101, CONDITION B
 SHOCK: MIL-STD-202, METHOD 213, CONDITION B
 VIBRATION: MIL-STD-202, METHOD 204, CONDITION B
 MOISTURE: MIL-STD-202, METHOD 106

RECOMMENDED SOLDER LAND PATTERN*



* NOTE: THIS PATTERN IS FOR REFERENCE ONLY. PATTERN MAY VARY DEPENDING ON ASSEMBLY PROCESS, BOARD TYPE, OR SPECIFIC ELECTRICAL OR MECHANICAL REQUIREMENTS.

DRAWING NO. C - 133-3711-311/320	
0	REVISIONS
ENGINEERING RELEASE	
1	9-17-98 R H B 10-15-98 ECN 45854
CHANGED: 750 PCS WAS 500 PCS	
* REVISION NUMBER FOLLOWED BY AN ALPHA *	
* CHARACTER INDICATES DRAWING CLARITY *	
* CATION OR PART NUMBER ADDITION ONLY *	
1a	12-1-98 R H B 12-4-98 ECN 46032
CHANGED: .000 ± .003 WAS .003 ± .006	
2	4-5-99 R H B ECN 46291
UPDATE DRAWING FOR 'D' FLAT BOTTOM INSULATOR. 5.6 LBS MAX ENGAGE WAS 3.4 LBS. 1.0 LB MIN DISENGAGE WAS 5 LBS TYPICAL. ADDED 8.0 LBS MAX DISENGAGE.	
3	6-27-01 R H B ECN 47895

CUSTOMER DRAWING

THIS DRAWING TO BE INTERPRETED PER ANSI Y 14.5M - 1982

"μSTATION"

COMPANY CONFIDENTIAL

TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN BY RJB	DATE 8-11-98	JOHNSON Cinch Connectivity Solutions 299 Johnson Ave. Ste. 100 Warren, MI 48093 1-800-247-8256	
DECIMALS .XX	CHECKED BY	DATE	TITLE JACK ASSEMBLY RA SURFACE MOUNT MCX	
XXX	APPROVED BY RJB	DATE 9-24-98	CODE NO.	
MATL	APPROVED BY	DATE	DRAWING NO. C - 133-3711-311/320	
FINISH	RELEASE DATE	10-15-98	SCALE 10:1 U/N INCH SHEET 2 OF 2	